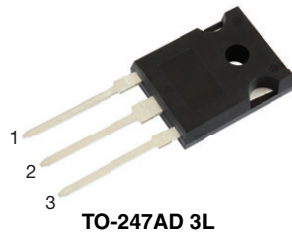


Dual High Voltage TMBS[®] (Trench MOS Barrier Schottky) Rectifier

 Ultra Low $V_F = 0.46\text{ V}$ at $I_F = 5.0\text{ A}$


FEATURES

- Trench MOS Schottky technology
- Low forward voltage drop, low power losses
- High efficiency operation
- Solder bath temperature 275 °C maximum, 10 s per JESD 22-B106
- AEC-Q101 qualified available:
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

MECHANICAL DATA

Case: TO-247AD 3L

Molding compound meets UL 94 V-0 flammability rating
 Base P/N-M3 - halogen-free, RoHS-compliant
 Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

Mounting torque: 10 in-lbs maximum

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 30 A
V_{RRM}	150 V
I_{FSM}	350 A
V_F at $I_F = 30\text{ A}$ ($T_J = 125\text{ °C}$)	0.70V
T_J max.	175 °C
Package	TO-247AD 3L
Circuit configuration	Common cathode

MAXIMUM RATINGS ($T_A = 25\text{ °C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VX60M153PW	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	150	V
Maximum average forward rectified current (fig. 1)		per device	60
		per diode	30
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	350	A
Operating junction temperature range	T_J ⁽¹⁾	-40 to +175	°C
Storage temperature range	T_{STG}	-40 to +175	

Note

⁽¹⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I _F = 5 A	T _J = 25 °C	V _F ⁽¹⁾	0.55	-	V
	I _F = 15 A			0.74	-	
	I _F = 30 A			0.94	1.07	
	I _F = 5 A	T _J = 125 °C		0.46	-	
	I _F = 15 A			0.59	-	
	I _F = 30 A			0.70	0.75	
Reverse current at rated V _R per diode	V _R = 100 V	T _J = 25 °C	I _R ⁽²⁾	0.0023	-	mA
		T _J = 125 °C		3.5	-	
	V _R = 150 V	T _J = 25 °C		-	0.25	
		T _J = 125 °C		10	25	
Typical junction capacitance	4.0 V, 1 MHz		C _J	1210	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)			
PARAMETER	SYMBOL	VX60M153PW	UNIT
Typical thermal resistance per device	R _{θJC} ⁽¹⁾	0.6	°C/W

Note

- (1) Thermal resistance junction-to-case to follow JEDEC® 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
VX60M153PW-M3/P	5.64	P	25/tube	Tube
VX60M153PWHM3/P ⁽¹⁾	5.64	P	25/tube	Tube

Note

- (1) AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)

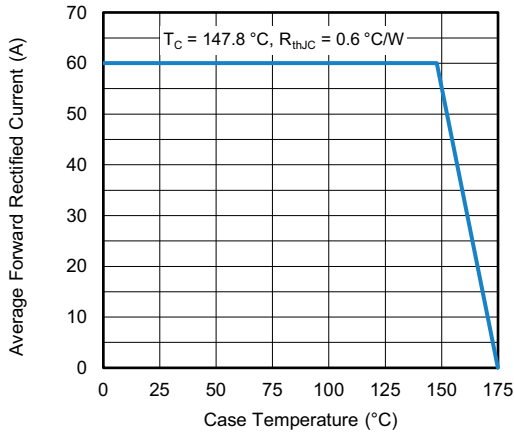


Fig. 1 - Maximum Forward Current Derating Curve

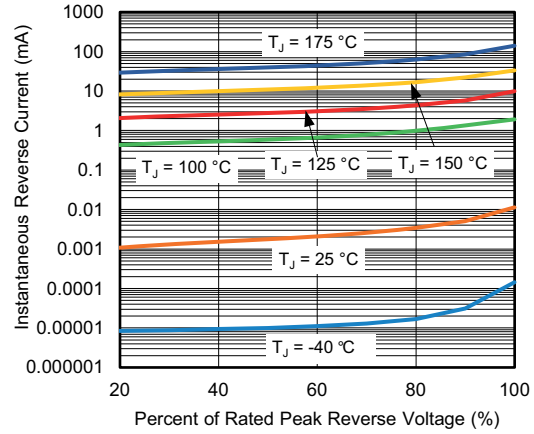


Fig. 4 - Typical Reverse Leakage Characteristics

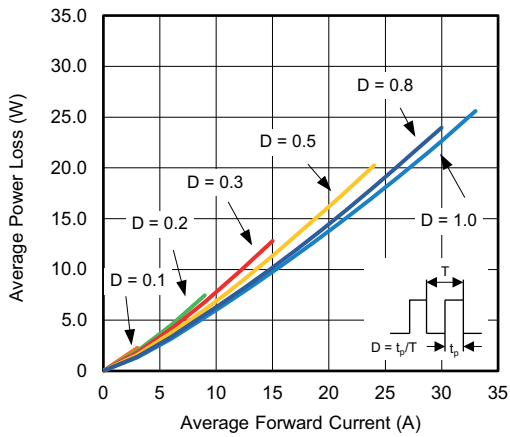


Fig. 2 - Average Power Loss Characteristics

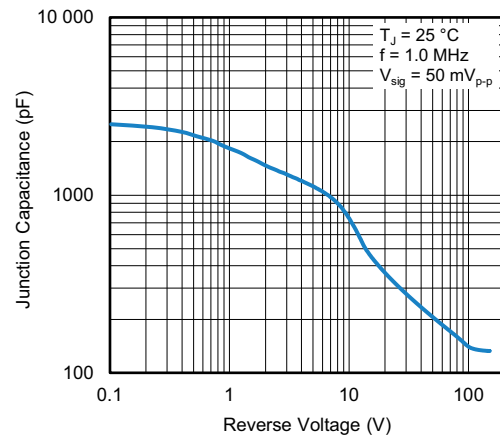


Fig. 5 - Typical Junction Capacitance

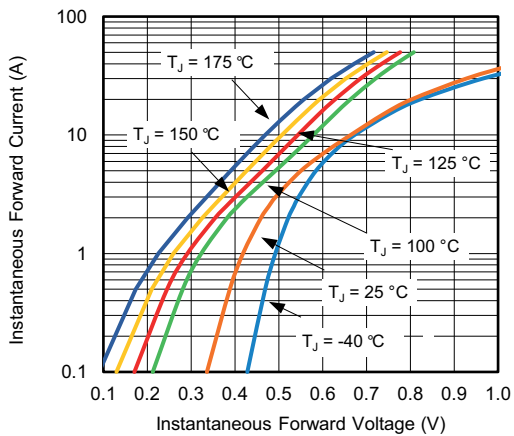


Fig. 3 - Typical Instantaneous Forward Characteristics

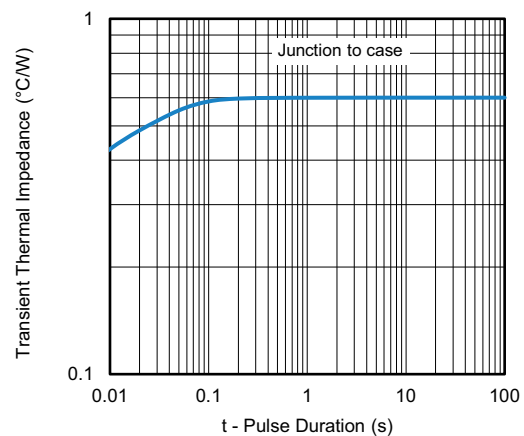
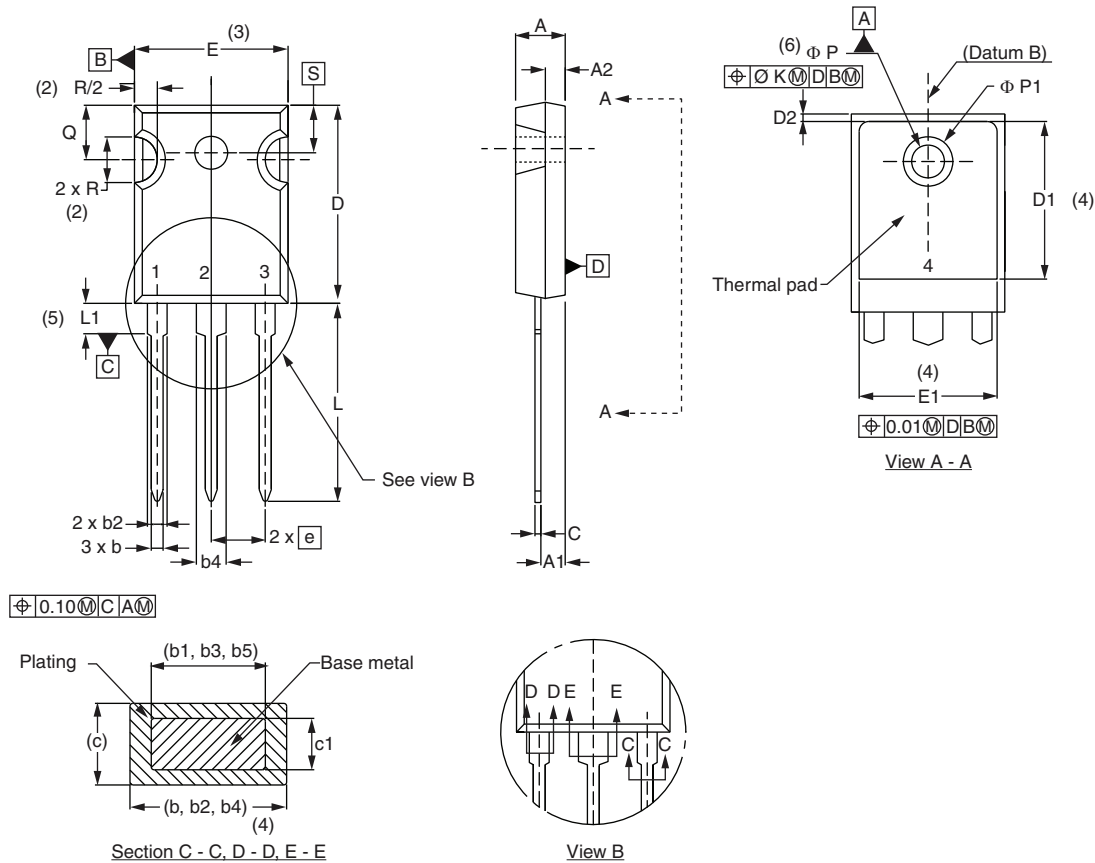


Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in millimeters (inches) **TO-247AD 3L**


SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209		D2	0.51	1.30	0.020	0.051	
A1	2.21	2.59	0.087	0.102		E	15.29	15.87	0.602	0.625	3
A2	1.50	2.49	0.059	0.098		E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055		e	5.46 BSC		0.215 BSC		
b1	0.99	1.35	0.039	0.053		Ø K	0.254		0.010		
b2	1.65	2.39	0.065	0.094		L	19.81	20.32	0.780	0.800	
b3	1.65	2.34	0.065	0.092		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		Ø P	3.56	3.66	0.14	0.144	
b5	2.59	3.38	0.102	0.133		Ø P1	-	6.98	-	0.275	
c	0.38	0.89	0.015	0.035		Q	5.31	5.69	0.209	0.224	
c1	0.38	0.84	0.015	0.033		R	4.52	5.49	0.178	0.216	
D	19.71	20.70	0.776	0.815	3	S	5.51 BSC		0.217 BSC		
D1	13.08	-	0.515	-	4						

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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